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	Туре	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L1	697	electroplating near8 (conc\$6 or (spacing with (anode or cathode)))	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/07/28 14:23
2	BRS	L2	524	1 and (@ad<20010719)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/07/28 14:23
3	BRS .	L4	1216	electroplat\$6 near8 (concentration or (spacing with (anode or cathode)))	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/07/28 14:24
4	BRS	<b>L</b> 5	944	4 and (@ad<20010719)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/07/28 14:25
5	BRS	<b>L</b> 6	641	5 and (change or changed or changing or revise or revising or revised or alter or altering or control or controlled or controlling)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/07/28 14:26

	Туре	L #	Hits	Search Text	DBs	Time Stamp
6	BRS	L7	416	6 and (Cu or copper)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/07/28 14:26

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	Туре	L #	Hits	Search Text	DBs	Time Stamp		
6	BRS	L6	416	(((electroplat\$6 near8 (concentration or (spacing with (anode or cathode)))) and (@ad<20010719)) and (change or changed or changing or revise or revising or revised or alter or altering or control or controlled or controlling)) and (Cu or copper)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/07/29 09:49		
7	IS&R	L8	2	("6685814").PN.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/07/29 10:20		
8	BRS	L9	3	electroplating or electroplated) with concentration with (spacing near4 (anode or cathode))		2004/07/29 10:23		
9	BRS	L10	1976	near4 (anode or cathode)))	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/07/29 10:24		
10	BRS	L11	205	10 same thickness	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/07/29 10:25		

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	Туре	L#	Hits	Search Text	DBs	Time Stamp
11	BRS	L12	164	11 and (@ad<20010719)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/07/29 10:25

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